

Designator	Description	Manufacturer	PartNumber	Quantity
C1	CAP, Film, 0.047uF, 310Vac, +/-10%, TH	Vishay	BFC233920473	1
C2, C8	CAP, CERM, 10uF, 50V, +/-10%, X7R, 1210	MuRata	GRM32ER71H106KA12L	2
C3	CAP, CERM, 2.2uF, 10V, +/-10%, X7R, 0603	MuRata	GRM188R71A225KE15D	1
	CAP, CERM, 0.1uF, 630V, +/-10%, X7T, 1210	TDK	C3225X7T2J104K	3
C6, C11, R14	NA	NA	NA	NA
C7	CAP, CERM, 2200pF, 250VAC, X1Y1, TH	Murata	DE1E3KX222MA4BL01	1
C9	CAP AL, 470uF, 50V, +/-20%, 0.022 ohm, 12.5x20TH	Panasonic	EEUFR1H471	1
D1	Diode, Switching-Bridge, 600V, 0.8A, MiniDIP	Diodes Inc.	RH06-T	1
D3	Diode 150V, 0.2A, 50nS, SOD-123	Diodes Inc.	BAV20W-7-F	1
D4	Diode, Ultrafast, 75V, 0.15A, SOD-523F	Comchip	CDSU4148	1
D5	Diode, TVS, 300V, 400W, SMA	Littelfuse	SMAJ300ALFCT	1
D6	Diode, Ultrafast, 600V, 1A, SMA	Diodes Inc.	US1J-13-F	1
D7	Diode, Schottky, 100V, 3A, SMB	MCC	SK310B-LTP	1
F1	Fuse - 875_Series, Slo-Blo, 0.5A, 250V, UL, CSA,	Littelfuse	0875.500MXEP	1
L1	Inductor, Drum Ferrite 3.3mH 0.15A, 6.16ohm, TH	Sumida	RCH895NP-332K	1
Q1	MOSFET N-CH, 2.5A, 800V, 4.5ohm, 19nC	ST	STD3NK80Z-1	1
R1, R2	RES Metal Film, 3.3ohm, 5%, 1W, TH	Panasonic	ERG-1SJ033	2
R3, R4	RES, 150k ohm, 5%, 0.25W, 1206	Vishay-Dale	CRCW1206150KJNEA	2
R5	RES, 10.0 ohm, 1%, 0.125W, 0805	Vishay-Dale	CRCW080510R0FKEA	1
R6	RES, 17.8k ohm, 1%, 0.1W, 0603	Vishay-Dale	CRCW060317K8FKEA	1
R7	RES, 75.0k ohm, 1%, 0.1W, 0603	Vishay-Dale	CRCW060375K0FKEA	1
R8	RES, 13.0k ohm, 1%, 0.1W, 0603	Vishay-Dale	CRCW060313K0FKEA	1
R9	RES, 15.8k ohm, 1%, 0.25W, 1206	Vishay-Dale	CRCW120615K8FKEA	1
R10	RES, 0 ohm, 5%, 0.1W, 0603	Vishay-Dale	CRCW06030000Z0EA	1
R12	RES, 0 ohm, 5%, 0.25W, 1206	Vishay-Dale	CRCW12060000Z0EA	1
R13	RES, 2.55 ohm, 1%, 0.25W, 1206	Vishay-Dale	CRCW12062R55FKEA	1
R15	RES, 680k ohm, 5%, 0.25W, 1206	Vishay-Dale	CRCW1206680KJNEA	1
R16	RES, 1.00k ohm, 1%, 0.1W, 0603	Vishay-Dale	CRCW06031K00FKEA	1
T1	Transformer EE-16	Wurth	750845150	1
U1	Off-Line Primary Side Sensing Controller with PFC	TI	TPS92314A	1
VDR1	Varistor 275V	EPCOS	S07K275E2	1

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